VPS10



CRT Display Video Output Amplifier: High-Voltage, Wideband Amplification

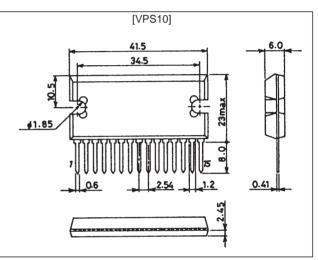
Features

- High output voltage and wide bandwidth make the VPS10 optimal for use in f_H (horizontal deflection frequency) = 85 kHz class color monitors.
 - (f = 100 MHz -3 dB at V_{OUT} = 50 Vp-p)
- SIP molded 15-pin package with three channels in a single package.

Package Dimensions

unit: mm

2127



Specifications

Absolute Maximum Ratings at $Ta = 25^{\circ}C$

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V _{CC} max		120	V
	V _{BB} max		15	V
Allowable power dissipation	Pd max	Tc = 25°C with an ideal heat sink	25	W
Junction temperature	Tj max		150	°C
Case temperature	Tc max		100	°C
Storage temperature	Tstg		-20 to +110	°C

Operating Conditions at $Ta=25^{\circ}C$

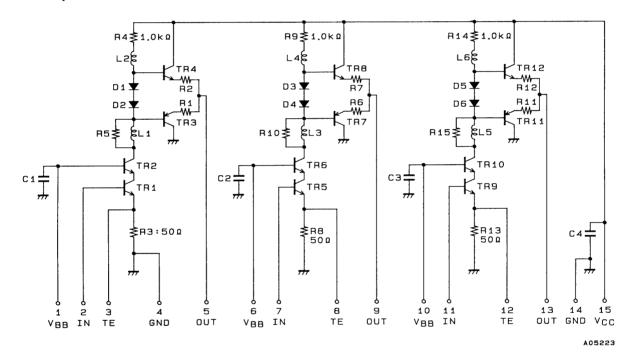
Parameter	Symbol Conditions		Ratings	Unit
Recommended supply voltage I	V _{CC}		80	V
	V _{BB}		10	V
	V _{CC}		90	V
Recommended supply voltage II	V _{BB}		10	V

SANYO Electric Co., Ltd. Semiconductor Bussiness Headquarters TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110 JAPAN

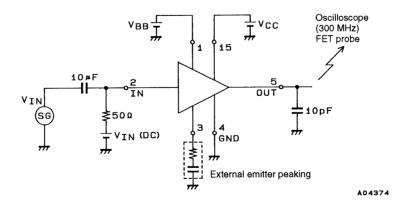
Parameter	notor Symbol	Oraditions	Ratings			1.114
Parameter	Symbol	Conditions	min	typ	max	Unit
Frequency band I (-3 dB)	f _c	V_{CC} = 80 V, V_{BB} = 10 V, C_L = 10 pF, V_{IN} (DC) = 2.7 V, V_{OUT} (p-p) = 40 V		100		MHz
Frequency band II	t _c	V_{CC} = 90 V, V_{BB} = 10 V, C_L = 10 pF, V_{IN} (DC) = 3.0 V, V_{OUT} (p-p) = 50 V		100		MHz
Pulse response characteristics	tr	V_{CC} = 80 V, V_{BB} = 10 V, C_L = 10 pF, V_{IN} (DC) = 2.7 V,		5.0		ns
	t _f	V _{OUT} (p-p) = 40 V		3.5		ns
Voltage gain	GV (DC)		17	19	21	times
Current drain I	I _{CC} 1			43		mA
Current drain i	I _{CC} 2			60		mA
Current drain II	I _{CC} 1			50		mA
	I _{CC} 2			75		mA

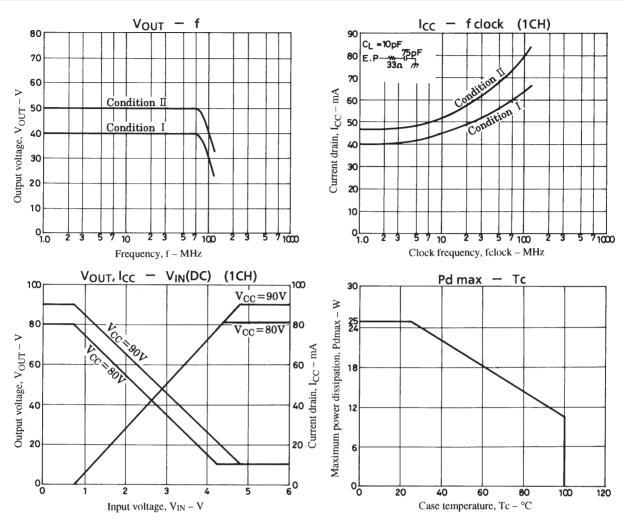
Electrical Characteristics at $Ta = 25^{\circ}C$ (for a single channel)

Internal Equivalent Circuit



Test Circuit (for a single channel)





Thermal Design

Since the VPS10 includes three channels as shown in the internal equivalent circuit diagram, we first consider a single channel. The chip temperature of each transistor under actual operating conditions is determined using the following formula.

Tj (TRi) = θ j-c (TRi) × P_C (TRi) + Δ Tc + Ta (°C)(1)

θj-c (Tri): Thermal resistance of an individual transistor

P_C (Tri): Collector loss for an individual transistor

 ΔTc : Case temperature rise

Ta: Ambient temperature

The θj -c (Tri) for each chip is:

 θj -c (TR1) to (TR4) = 30°C/W.....(2)

Although the loss for each transistor in a video pack varies with frequency and is not uniform, if we assume operation at the maximum operating frequency, f = 100 MHz (clock), then the chips with the largest loss will be the emitter-follower stage transistors (TR3 and TR4) and that loss will be about 20% of the total loss. Thus from the Pd (shown in the figure) for a single channel we have:

 P_C (E and F stages)_{f = 100 MHz} = Pd (1ch)_{f = 100 MHz} × 0.20 [W](3)

Here, we must select a heat sink with a capacity θ h such that the Tj of these transistors does not exceed 150°C. Equation (4) below gives the relationship between θ h and Δ Tc.

 $\Delta Tc = Pd (TOTAL) \times \thetah$(4) The required θ h is calculated using this equation and equation (1).

VPS10 Thermal Design Example

Conditions: Using an $f_H = 85$ kHz class monitor, $f_V = 100$ MHz (clock)

 $V_{CC} = 90 \text{ V}, V_{BB} = 10 \text{ V}, V_{OUT} = 50 \text{ Vp-p} (C_L = 10 \text{ pF})$

Consider the case where the maximum clock frequency is 100 MHz, taking into account the fact that this class of monitor can be operated at ambient temperatures up to $Ta = 60^{\circ}C$.

As mentioned previously, the chips with the largest loss are the transistors in the emitter-follower stage. Determining those values gives:

 P_{C} (E and F stages) = 7.2 × 0.20 = 1.44 [W].....(5)

We determine ΔTj by substituting the value for θj -c in equation (5).

 $\Delta T j = 1.44 \times 30 = 43.2 [^{\circ}C]$

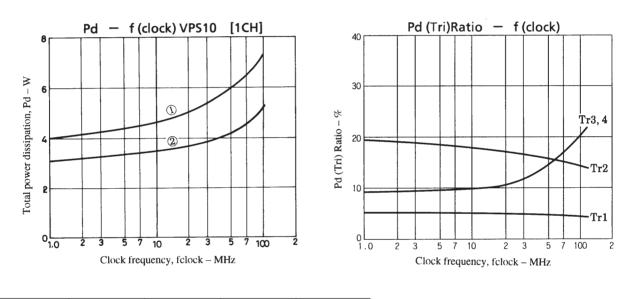
Therefore, Tj (max) will be 43.2 + Tc (max) = 43.2 + 100. Since this will be under $100^{\circ}C$, it suffices to design a heat sink that guarantees that Tc will be under $100^{\circ}C$.

Therefore, a heat sink such that $Tc < 100^{\circ}C$ will have the following thermal resistance:

 $\theta h = \Delta Tc \div Pd (TOTAL) = (Tc - Ta) \div [Pd (1ch) \times 3] = 40 \div (7.2 \times 3) = 1.85^{\circ}C/W$

Thus the thermal resistance in this case is $\theta h = 1.8^{\circ}C/W$.

In actual practice, the ambient temperature and operating conditions will allow a heat sink smaller than that indicated by this calculation to be used. Therefore, design optimization taking the actual conditions into account is also required.



Item	V _{CC} (V)	V _{BB} (V)	V _{OUT} (V)	V _O (center)
1	90	10	50	50
2	80	10	40	45

- No products described or contained herein are intended for use in surgical implants, life-support systems, aerospace equipment, nuclear power control systems, vehicles, disaster/crime-prevention equipment and the like, the failure of which may directly or indirectly cause injury, death or property loss.
- Anyone purchasing any products described or contained herein for an above-mentioned use shall:
 - ① Accept full responsibility and indemnify and defend SANYO ELECTRIC CO., LTD., its affiliates, subsidiaries and distributors and all their officers and employees, jointly and severally, against any and all claims and litigation and all damages, cost and expenses associated with such use:
 - ② Not impose any responsibility for any fault or negligence which may be cited in any such claim or litigation on SANYO ELECTRIC CO., LTD., its affiliates, subsidiaries and distributors or any of their officers and employees jointly or severally.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. SANYO believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

This catalog provides information as of December, 1997. Specifications and information herein are subject to change without notice.